



Material Content Data Sheet



Sales Product Name		BSC032N04LS		Issued		22. July 2019		
MA#		MA005345383						
Package		PG-TDSON-8-51		Weight*		101.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.447	0.44	0.44	4404	4404
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		134	
	non noble metal	zinc	7440-66-6	0.055	0.05		537	
	non noble metal	iron	7439-89-6	1.090	1.07		10733	
wire	non noble metal	copper	7440-50-8	44.271	43.60	44.73	435810	447214
	noble metal	gold	7440-57-5	0.027	0.03	0.03	268	268
encapsulation	organic material	carbon black	1333-86-4	0.088	0.09		870	
	plastics	epoxy resin	-	4.068	4.00		40042	
	inorganic material	silicondioxide	60676-86-0	40.057	39.43	43.52	394322	435234
leadfinish	non noble metal	tin	7440-31-5	1.264	1.24	1.24	12440	12440
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	286	286
solder	noble metal	silver	7440-22-4	0.017	0.02		168	
	non noble metal	tin	7440-31-5	0.034	0.03		336	
	non noble metal	lead	7439-92-1	0.631	0.62	0.67	6209	6713
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	zinc	7440-66-6	0.011	0.01		112	
	non noble metal	iron	7439-89-6	0.228	0.22		2243	
	non noble metal	copper	7440-50-8	9.250	9.11	9.34	91058	93441
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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